

Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are referenced to SOURCE lead. ($T_{\text{Ambient}} = 25^{\circ}\text{C}$ unless otherwise specified). PCB mounting uses the standard footprint with 70 μm copper thickness.

Symbol	Parameter	Min.	Max.	Units	Test Conditions
V_{ds}	Maximum drain to source voltage	—	47	V	
V_{in}	Maximum input voltage	-0.3	7		
$I_{\text{in, max}}$	Maximum IN current	-10	+10	mA	
$I_{\text{sd cont.}}$	Diode max. continuous current ⁽¹⁾			A	
	$r_{\text{th}}=100^{\circ}\text{C/W}$	—	1.6		D-Pak Std footprint
	$r_{\text{th}}=5^{\circ}\text{C/W}$	—	18		D-Pak with $R_{\text{th}}=5^{\circ}\text{C/W}$
	$r_{\text{th}}=50^{\circ}\text{C/W}$	—	3		D-Pak with sq. footprint
$I_{\text{sd pulsed}}$	Diode max. pulsed current ⁽¹⁾	—	18		
P_{d}	Maximum power dissipation ⁽¹⁾			W	
	$r_{\text{th}}=50^{\circ}\text{C/W}$	—	2.5		
	$r_{\text{th}}=100^{\circ}\text{C/W}$	—	1.25		
ESD1	Electrostatic discharge voltage (Human Body)	—	4	kV	$C=100\text{pF}$, $R=1500\Omega$,
ESD2	Electrostatic discharge voltage (Machine Model)	—	0.5		$C=200\text{pF}$, $R=0\Omega$, $L=10\mu\text{H}$
$T_{\text{stor.}}$	Max. storage temperature	-55	150		
$T_{\text{j max.}}$	Max. junction temperature	-40	+150	$^{\circ}\text{C}$	
T_{lead}	Lead temperature (soldering, 10 seconds)	—	300		

Thermal Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$R_{\text{th 1}}$	Thermal resistance with standard footprint	—	100	—	$^{\circ}\text{C/W}$	D-PAK
$R_{\text{th 2}}$	Thermal resistance with 1" square footprint	—	50	—		
$R_{\text{th 3}}$	Thermal resistance junction to case	—	3	—		

Recommended Operating Conditions

These values are given for a quick design. For operation outside these conditions, please consult the application notes.

Symbol	Parameter	Min.	Max.	Units
$V_{\text{ds (max)}}$	Continuous drain to source voltage	—	35	V
V_{IH}	High level input voltage	4	6	
V_{IL}	Low level input voltage	0	0.5	
I_{ds} $T_{\text{amb}}=85^{\circ}\text{C}$	Continuous drain current			A
	$T_{\text{Ambient}} = 85^{\circ}\text{C}$, $I_{\text{N}} = 5\text{V}$, $r_{\text{th}} = 50^{\circ}\text{C/W}$, $T_{\text{j}} = 125^{\circ}\text{C}$ 1" sq. footprint	—	3.3	
	$T_{\text{Ambient}} = 85^{\circ}\text{C}$, $I_{\text{N}} = 5\text{V}$, $r_{\text{th}} = 100^{\circ}\text{C/W}$, $T_{\text{j}} = 125^{\circ}\text{C}$ Std. footprint	—	2	
R_{in}	Recommended resistor in series with IN pin	0.2	5	$\text{k}\Omega$
$T_{\text{r-in(max)}}$	Max recommended rise time for IN signal (see fig. 2)	—	1	μs
$F_{\text{r-Isc}}^{(2)}$	Max. frequency in short circuit condition ($V_{\text{cc}} = 14\text{V}$)	0	1	kHz

(1) Limited by junction temperature (pulsed current limited also by internal wiring)

(2) Operations at higher switching frequencies is possible. See Application. Notes.

Static Electrical Characteristics

(T_j = 25°C unless otherwise specified.)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
R _{ds(on)}	ON state resistance T _j = 25°C	20	45	60	mΩ	V _{in} = 5V, I _{ds} = 1A
R _{ds(on)}	ON state resistance T _j = 150°C	—	75	100		
I _{dss} @T _j =25°C	Drain to source leakage current	0	0.5	25	μA	V _{cc} = 14V, T _j = 25°C
I _{dss2} @T _j =25°C	Drain to source leakage current	0	5	50		V _{cc} = 40V, T _j = 25°C
V _{clamp 1}	Drain to source clamp voltage 1	47	52	56	V	I _d = 20mA (see Fig.3 & 4)
V _{clamp 2}	Drain to source clamp voltage 2	50	53	60		I _d =I _{shutdown} (see Fig.3 & 4)
V _{in clamp}	IN to source clamp voltage	7	8.1	9.5		I _{in} = 1 mA
V _{th}	IN threshold voltage	1	1.6	2		I _d = 50mA, V _{ds} = 14V
I _{in, -on}	ON state IN positive current	25	90	200	μA	V _{in} = 5V
I _{in, -off}	OFF state IN positive current	50	130	250		V _{in} = 5V over-current triggered

Switching Electrical Characteristics

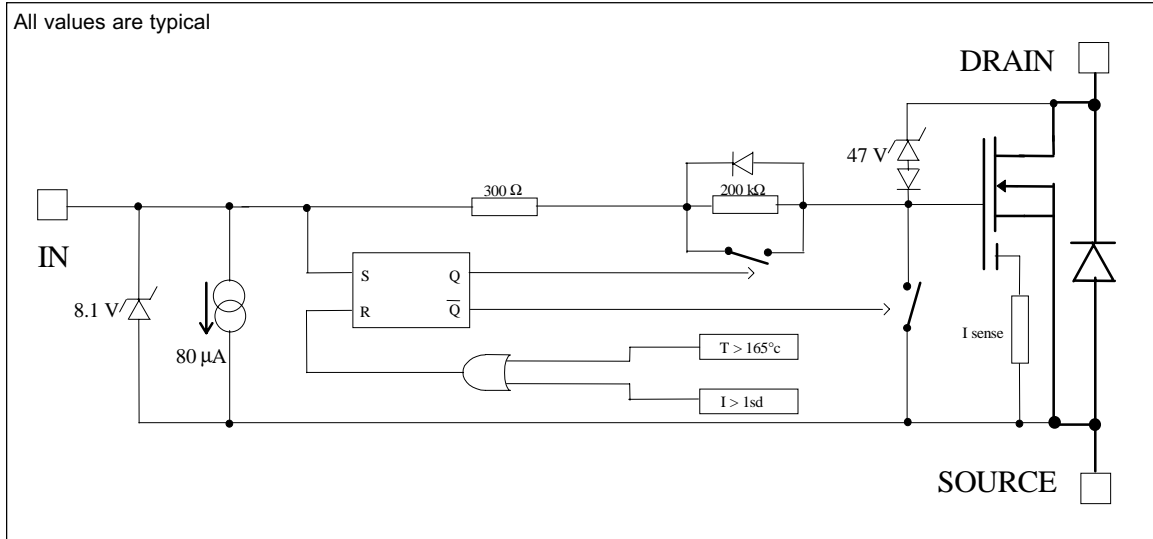
V_{cc} = 14V, Resistive Load = 5Ω, R_{input} = 50Ω, 100μs pulse, T_j = 25°C, (unless otherwise specified).

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
T _{on}	Turn-on delay time	0.05	0.3	0.6	μs	See figure 2
T _r	Rise time	0.4	1	2		
T _{rf}	Time to 130% final R _{ds(on)}	—	8	—		See figure 2
T _{off}	Turn-off delay time	0.8	2	3.5		
T _f	Fall time	0.5	1.5	2.5		
Q _{in}	Total gate charge	—	11	—	nC	V _{in} = 5V

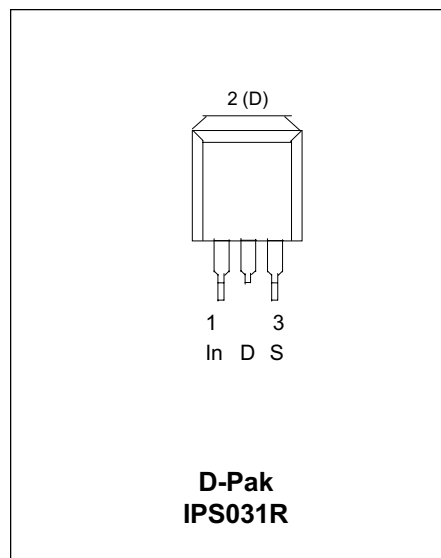
Protection Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
T _{sd}	Over temperature threshold	—	165	—	°C	See fig. 1
I _{sd}	Over current threshold	10	14	18	A	See fig. 1
V _{reset}	IN protection reset threshold	1.5	2.3	3	V	
T _{reset}	Time to reset protection	2	10	40	μs	V _{in} = 0V, T _j = 25°C
EOI_OT	Short circuit energy (see application note)	—	400	—	μJ	V _{cc} = 14V

Functional Block Diagram



Lead Assignments



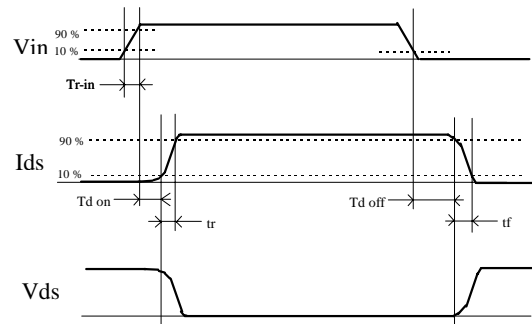


Figure 2 - IN rise time & switching time definitions

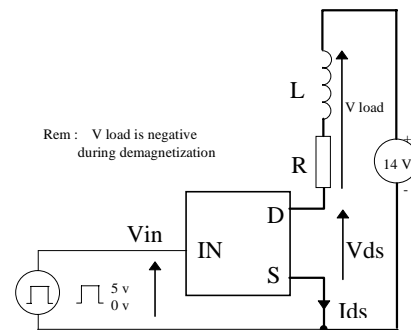


Figure 4 - Active clamp test circuit

All curves are typical values with standard footprints. Operating in the shaded area is not recommended.

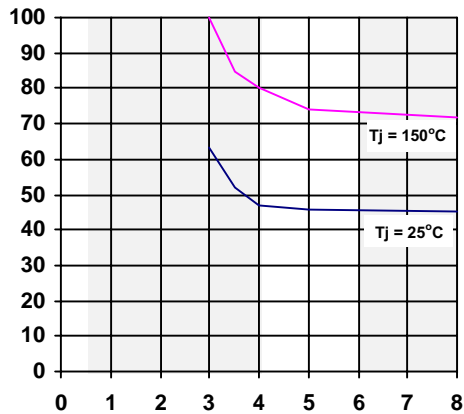


Figure 5 - Rds ON (mΩ) Vs Input Voltage (V)

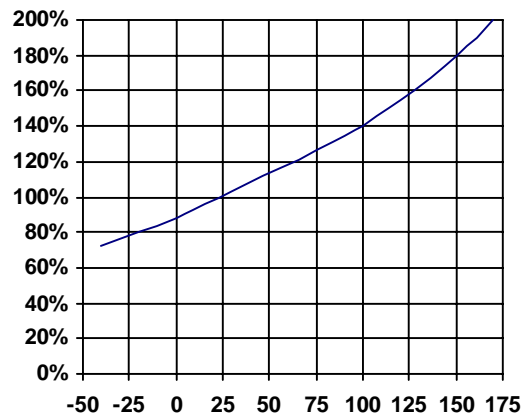


Figure 6 - Normalised Rds ON (%) Vs Tj (°C)

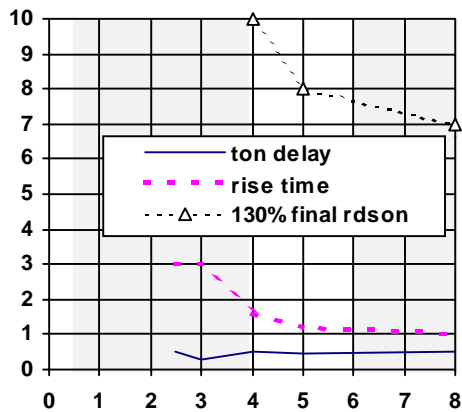


Figure 7 - Turn-ON Delay Time, Rise Time & Time to 130% final Rds(on) (us) Vs Input Voltage (V)

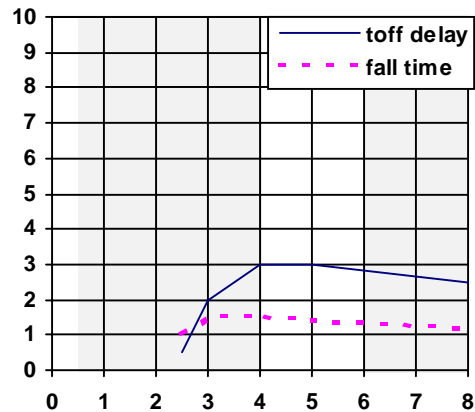


Figure 8 - Turn-OFF Delay Time & Fall Time (us) Vs Input Voltage (V)

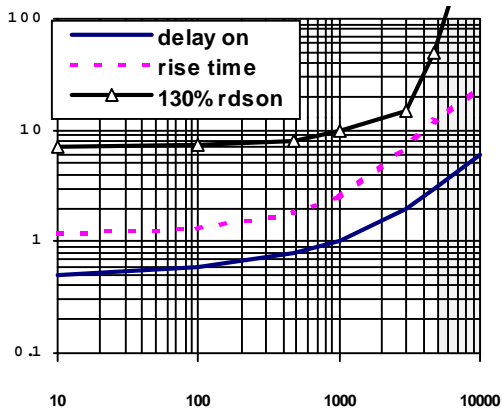


Figure 9 - Turn-ON Delay Time, Rise Time & Time to 130% final $R_{DS(on)}$ (us) Vs IN Resistor (Ω)

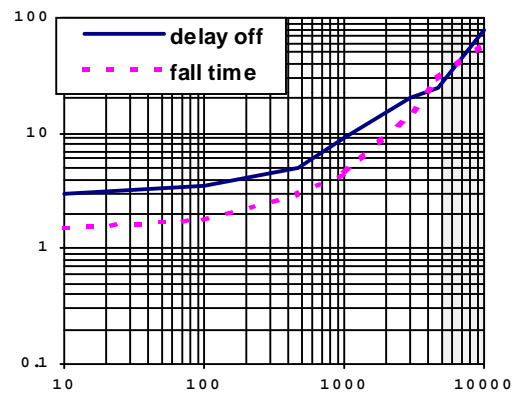


Figure 10 - Turn-OFF Delay Time & Fall Time (us) Vs IN Resistor (Ω)

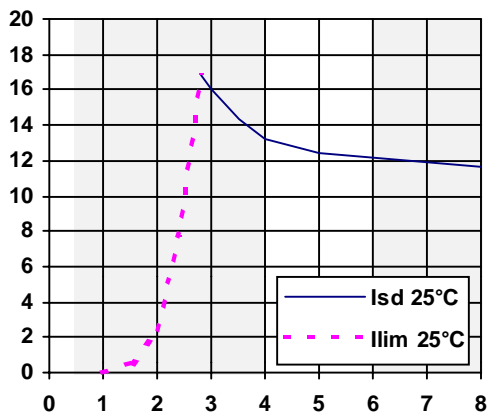


Figure 11 - Current limitation & I shutdown (A) Vs V_{in} (V)

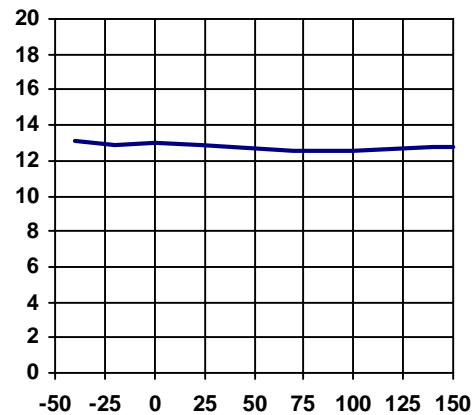


Figure 12 - I shutdown (A) Vs Temperature ($^{\circ}\text{C}$)

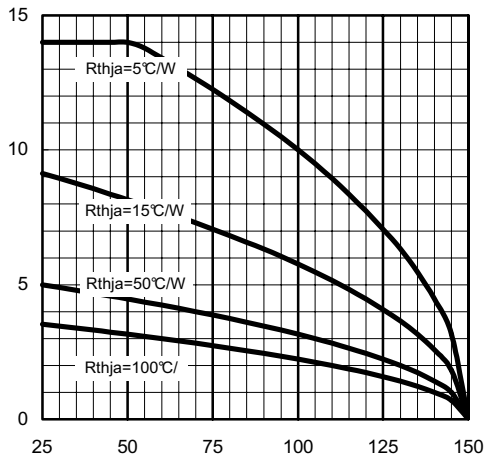


Figure 13 - Max. I load current (A) Vs Tamb (°C)
IPS031R

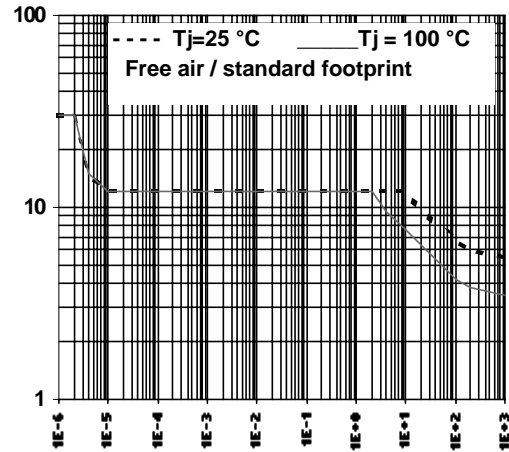


Figure 14 - Ids (A) Vs Protection Resp. Time (s)
IPS031R

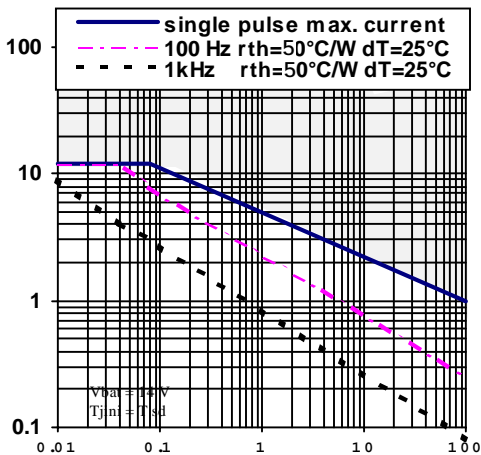


Figure 15 - Iclamp (A) Vs Inductive Load (mH)

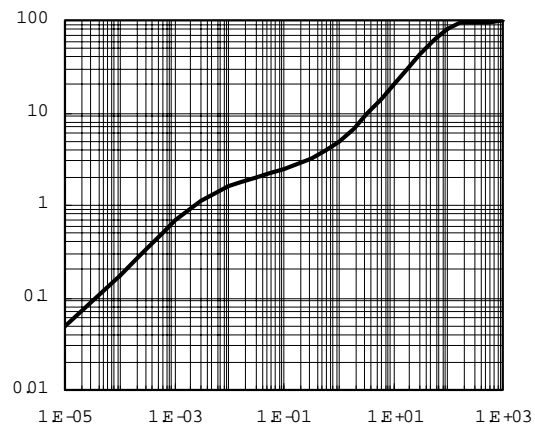


Fig.16 - Transient Thermal Impedance (°C/W)
Vs Time (s) - IPS031R

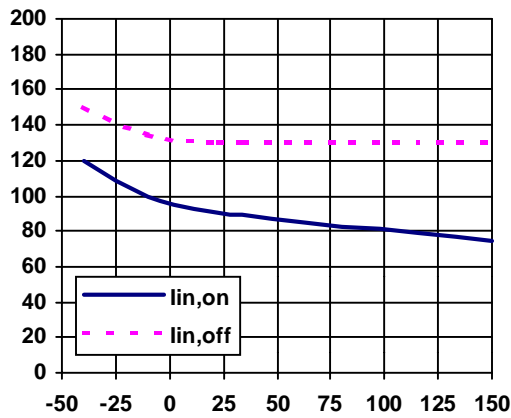


Figure 17 - Input current (µA) Vs Junction (°C)

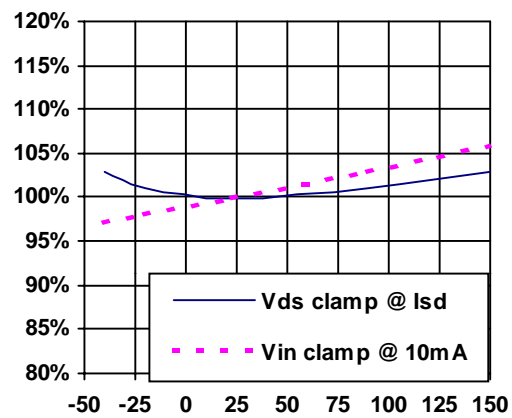


Figure 18 - Vin clamp and V clamp2 (%) Vs Tj (°C)

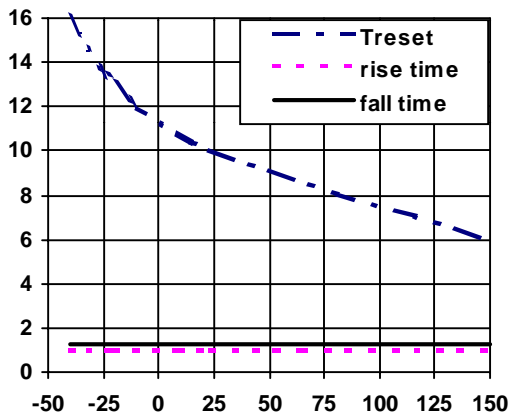
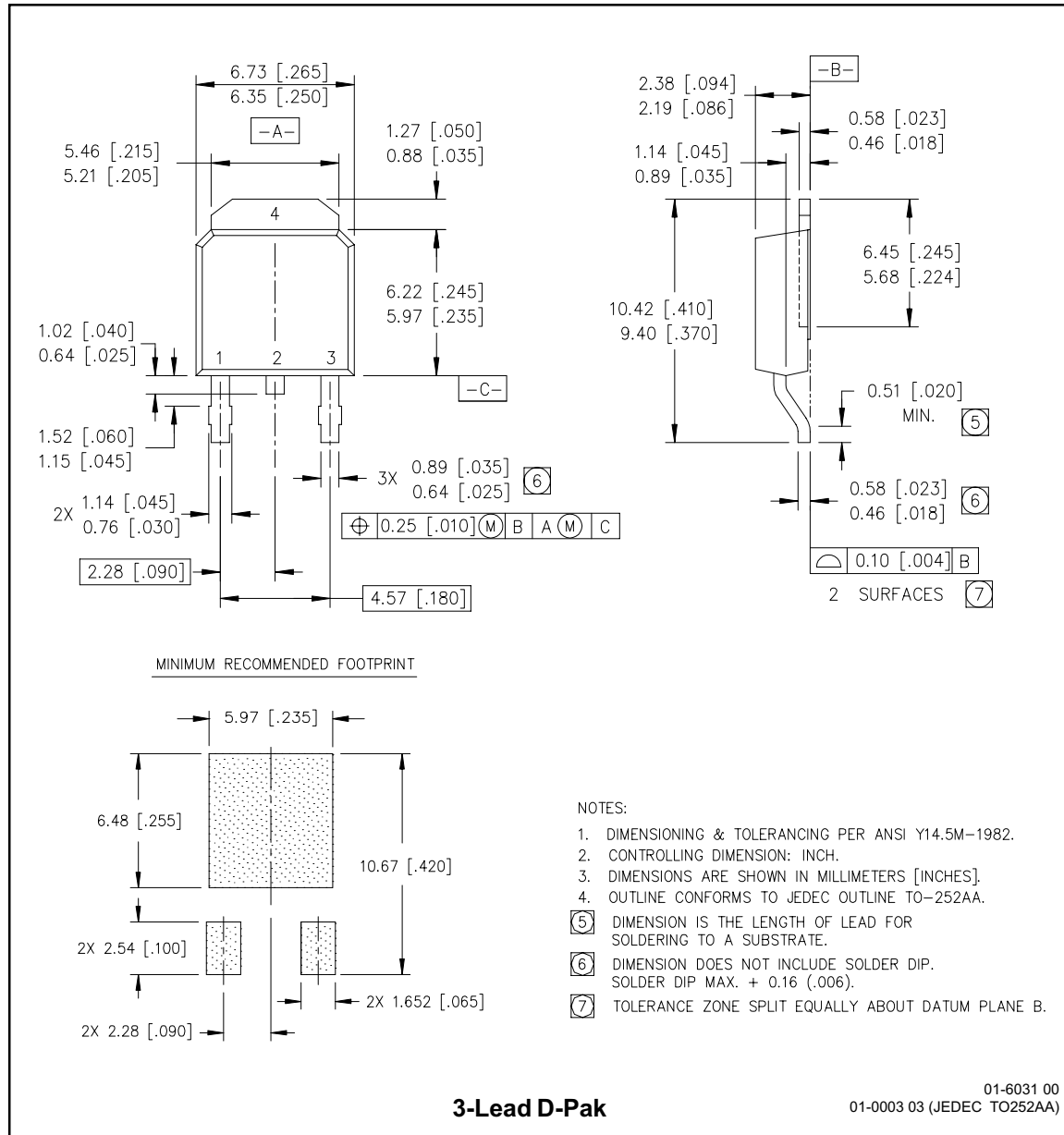


Figure 19 - Turn-on, Turn-off, and treset (µs) Vs Tj (°C)

Case Outline



Technical drawing of a TRR component showing top, side, and end views with dimensions in millimeters and inches.

Top View:

- Overall width: 41.10 [1.61] / 39.90 [1.53]
- Overall height: 18.85 [0.73] / 18.65 [0.65]
- Internal width: 16.10 [0.634]
- Internal height: 11.60 [0.457] / 11.40 [0.449]
- Top edge features: 1.60 [0.063] / 1.50 [0.059]
- Bottom edge features: 10.90 [0.429] / 10.70 [0.421]
- Bottom edge features: 16.10 [0.634]
- Internal hole diameter: $\phi 1.75$ [0.069] / 1.25 [0.049]

Side View:

- Top edge features: 0.368 [0.0145] / 0.342 [0.0135]
- Internal height: 24.30 [0.957] / 23.90 [0.941]
- Bottom edge features: 15.42 [0.609] / 15.22 [0.601]
- Bottom edge features: 4.72 [0.186] / 4.52 [0.178]

End View:

- Overall diameter: $\phi 360.00$ [14.173] MAX.
- Internal hole diameter: $\phi 13.52$ [0.532] / 12.80 [0.504]
- Internal hole diameter: $\phi 60.00$ [3.362] MIN.
- Internal hole diameter: 26.40 [1.039] / 24.40 [0.961]

NOTES:

1. OUTLINE CONFORMS TO EIA-481 & EIA-541.
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].

01-3072 00

Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>